

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An implant comprising
a sensor device being fixedly connected to a first end of a longitudinal carrier;
an inductive coil connected to the sensor device via electrical connection lines that are arranged on the longitudinal carrier; and
a covering encapsulating the sensor device, the carrier with the connection lines and the coil;
wherein the carrier has a sufficient rigidity such that the sensor device is adapted to be guided by the carrier during implantation to a target position and held in position at the target position, and that the covering part has means for providing a subcutaneous fastening, the carrier is in a substantially planar shape and ~~is bendable~~ moves from said planar shape to a shape wherein the carrier is arranged at an angle from 60° to 120° relative to the plane in which the coil windings of the inductive coil are arranged.
2. (Canceled)
3. (Previously Presented) The implant according to claim 1, wherein there are provided two connection lines between the coil and the sensor device.
4. (Previously Presented) The implant according to claim 1, wherein the carrier is flat.

5. (Previously Presented) The implant according to claim 1, further comprising a stiffening foil being provided in the covering part.
6. (Previously Presented) The implant according to claim 5, wherein the carrier is formed as at least one of a rod and a foil.
7. (Canceled)
8. (Previously Presented) The implant according to claim 1, wherein a frame is fastened at the first end of the carrier, the sensor device positively fits within the frame.
9. (Previously Presented) The implant according to claim 8, wherein the frame is formed one piece with the carrier.
10. (Previously Presented) The implant according to claim 1, wherein the carrier is formed as a common carrier for the electrical connection lines and the coil windings.
11. (Previously Presented) The implant according to claim 1, wherein the sensor device comprises at least one pressure sensor.
12. (Previously Presented) The implant according to claim 1, wherein the covering part encapsulating the coil is adapted to be arranged in an interior of the brain.
13. (Previously Presented) The implant according to claim 12, wherein the encapsulating material of the covering part covering the sensor device is formed as a pressure transmitting medium.

14. (Previously Presented) The implant according to claim 1, wherein the sensor device is adapted to be positioned for at least one of an intraparenchymal and a intraventricular pressure measurement.

15. (Canceled)

16. (Previously Presented) An implant according to claim 12, wherein the covering part encapsulating the coil is adapted to be arranged in the epidural.

17. (Canceled)

18. (Previously Presented) An implant according to claim 13, wherein the carrier is bendable substantially about a line adjacent to said inductive coil.